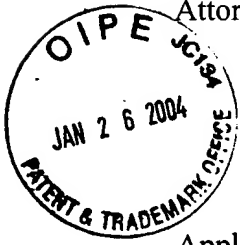


Application No.: 09/687,493
Attorney Docket: AMKOR-045A



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:	Sung Sik Jang)	Confirmation No.	9392
)		
Serial No.:	09/687,493)	Art Unit:	2826
)		
Filed:	10/13/2000)	Examiner:	Williams,
)		Alexander O.
For:	Semiconductor Package Having)		
	Improved Adhesiveness and Ground)		
	Bonding)		

AMENDMENT IN RESPONSE TO OFFICE ACTION

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir/Madam:

In response to the Office Action mailed August 28, 2003 in relation to the above-identified patent application, please amend the application as follows:

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